REV	MODIFICATION	DRAWN	APPROVED

1. MATERIAL:

   HOUSING – 15% GLASS FILLED PBT (UL94V-0)

   CONTACT – C5191R-H ø0.45±0.01mm PHOSPHOR BRONZE

2. FINISH:

   PLEASE REFER TO THE ORDER INFORMATION

   PLATING : GOLD PLATING 1-3u" OVER NICKEL 50u" MIN.
   GOLD PLATING 6u" MIN. OVER NICKEL 50u" MIN.
   GOLD PLATING 15u" MIN. OVER NICKEL 50u" MIN.
   GOLD PLATING 30u" MIN. OVER NICKEL 50u" MIN.
   GOLD PLATING 50u" MIN. OVER NICKEL 95-110u"

3. ORDER INFORMATION

M012 – 8 X 1 1 – 1 X X

CIRCUIT
- 2 : 2C
- 4 : 4C
- 6 : 6C
- 8 : 8C

CONTACT PLATING
- 3 : GOLD PLATING 1-3u"
- 6 : GOLD PLATING 6u"
- B : GOLD PLATING 15u"
- C : GOLD PLATING 30u"
- D : GOLD PLATING 50u"

TAIL STYLE & COLOR
1. BLACK(DIP)
2. MEDIUM GRAY(DIP)

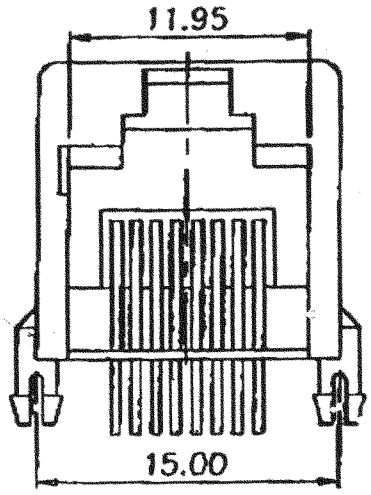
出圖章 88.5.18 R & D

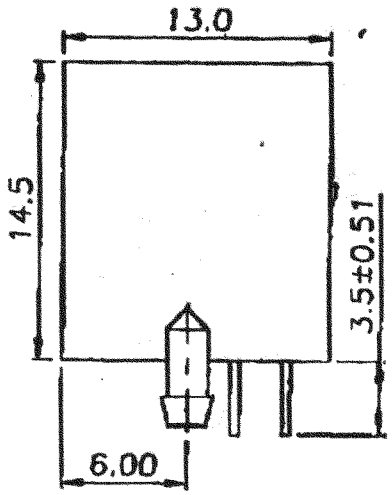
X.±	X.'±	M012-8811-11B	
.X±	.X'±		
.XX±	.XX'±	FILE NO.	DWG NO. M01-0001-0002
.XXX±	.XXX'±		
		TITLE: MODULAR JACK 8P DIP GROUND PIN SIDE ENTRY W/CHAMFER	
			SHEET 1/1 SIZE A

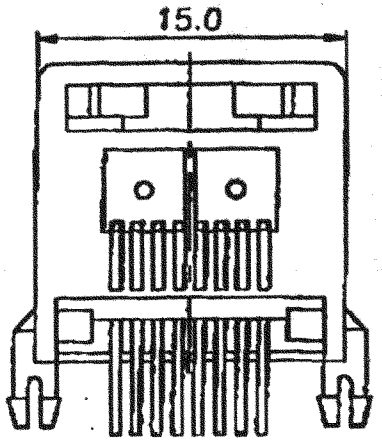
ST-DR-009A

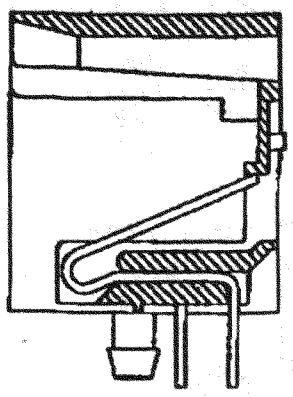
ARNDT # 115844

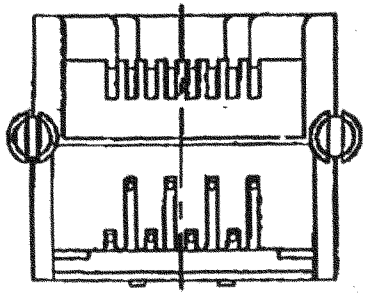
REV	MODIFICATION	DRAWN	APPROVED

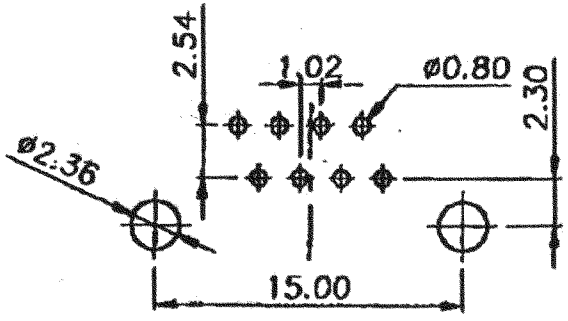












RECOMMENDED PCB LAYOUT

NOTE :
1. UNIT : mm

H
88.5.18
R & D

X.±	X.'±	M012-8811-11B
.X± 0.25	.X'±	
.XX± 0.15	.XX'±	M01-0001-0001
.XXX±	.XXX'±	
		MODULAR JACK 8P DIP GROUND PIN SIDE ENTRY W/CHAMFER
		1/1 A

ST-DR-009A